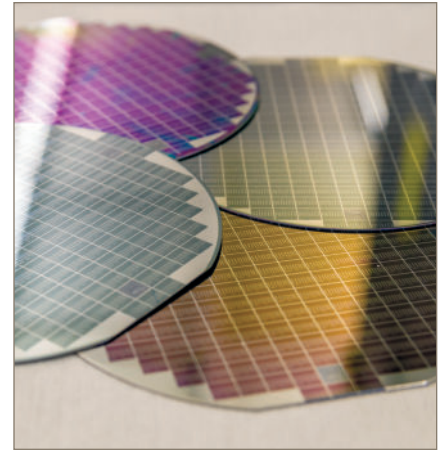


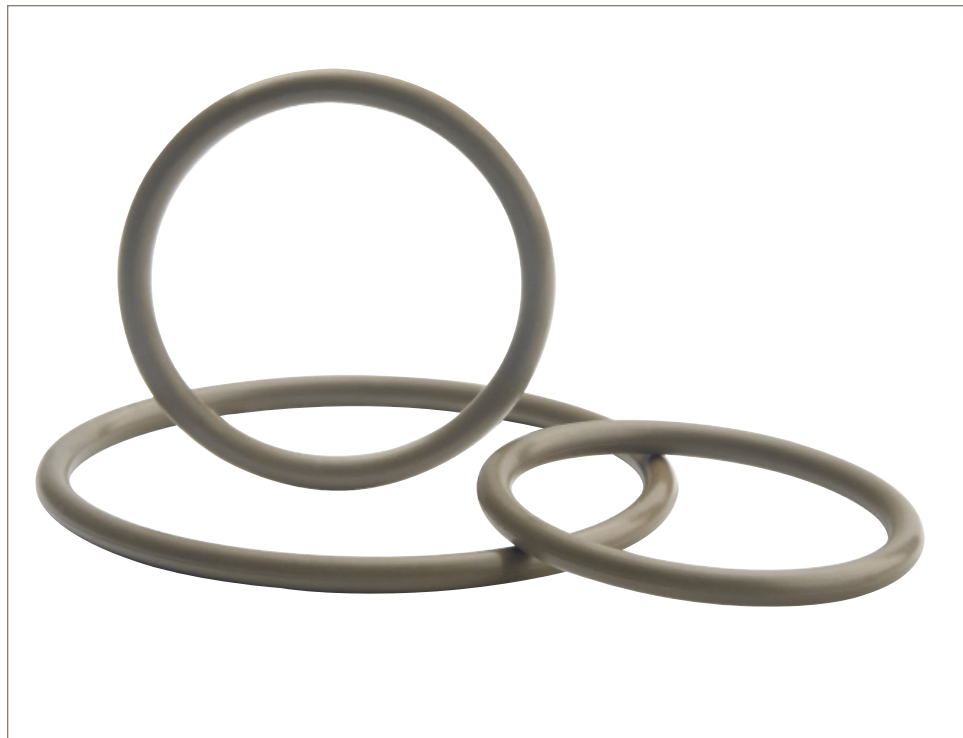
# FF308

High Purity and Plasma Resistant  
Perfluoroelastomer



## A Cost Effective Alternative:

FF308 delivers the high performance demanded in the semiconductor industry, but in a cost-effective manner. In today's operations, reducing the frequency of seal maintenance to keep processes up and running is imperative. However, when PM (preventative maintenance) intervals are well established, the responsible engineers begin to look at the reducing the cost of the consumable components themselves to achieve further cost savings. In these cases, FF308 is an excellent alternative to the costly premium grade FFKM solutions.



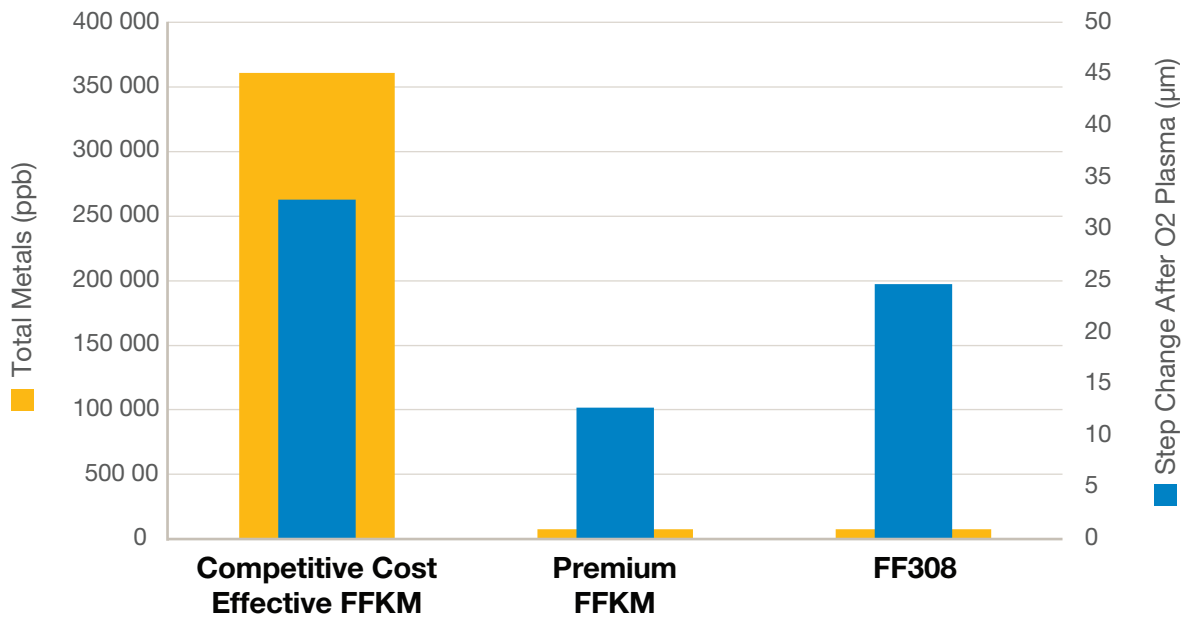
[Contact Us](#)

## Product Features:

- Maximum operating temperature: 275°C (527°F)
- Cost-effective sealing solution
- Low extractables
- Extremely low metallic ion content
- Great plasma resistance
- Available in EZ-Lok™, O-rings and custom shapes



ENGINEERING YOUR SUCCESS.



## Etch Resistance

FF308 provides great plasma resistance making it an excellent option for deposition and etch applications. Because FF308 exhibits a slower etch compared to other products of its class, the PM intervals of the incumbent materials can be maintained as cost savings are achieved.

## Purity

FF308 is a high purity solution, which reduces the risk of particle generation that can lead to on wafer defects. It outperforms materials in its class, finding itself with low metal levels typically only found in premium FFKMs.

PROPERTY	FF308
<b>Color</b>	Gray
<b>Original Physical Properties, ASTM D2240, D1414</b>	
Hardness, Shore A pts.	72
Tensile Strength, psi	1648
Tensile Modulus (100%), psi	700
Ultimate Elongation, %	150
<b>Compression Set, ASTM D395 Method B</b>	
70 hrs. @ 230°C (446°F), % of original deflection	36

